

**PRESS RELEASE**  
**FOR IMMEDIATE RELEASE**

The CONDENS-IT Profiler Low Cost Vapor Phase Reflow Soldering Machine family

Bad Bentheim, Germany March 16, 2018- **IMDES CREATIVE SOLUTIONS** is launching the **CONDENS-IT PROFILER** family a range of **LOW COST** Laboratory **Vapor Phase Reflow Soldering machines priced under US\$ 6000,-**  
**For people who want to learn or to analyses the vapor phase process is working, like students and engineers IMDES is consisting of also offering a special starters kit "Go Vapor Phase" consisting of CONDENS-IT MINI PROFILER lead free solder paste and heat transfer liquid Galden detailed manual with description of the process and a video at usb stick for an interesting price**



The **IMDES CONDENS-IT PROFILER** family the **MINI, JUMBO & DINO**, -are intended to use for reflow soldering printed circuit boards on the smaller scale, i.e. for individual pieces, proto types and small series.

They are specially designed to use it for developing purposes of prototyping PCB's using BGAs, LGA's components and stacked arrays.

Due the small foot print of the **IMDES CONDENS-IT PROFILER** family , forced air cooling, single phase you will able to place the unit fast on every place you want to use it.

After placing it is running quickly and ensures at the same time highest solder quality.

For intensive use, appropriately frequent checks and maintenance are required, due to the low GALDEN capacity .

Max. solder product formats;

MINI 250 x 190 x 20 mm (L x W x H) 9,84" x 7,48" x 0,78"

JUMBO 430 x 230 x 20 mm (L x W x H) 16,93" x 9,05" x 0,78"

DINO 580 x 460 x 20 mm (L x Wx H) 22,83" x 18,11" x 0,78"

### Features

- Table model Top loader
- Adjustable temperature profiles in the pre-heating zone (CVPRS\*)
- Adjustable TAL Time Above Liquid
- ATS Anti Tomb Stone modus
- Micro USB for the transfer of solder profile data to PC
- Window to observe the soldering process
- Suitable for BGA's, Stacked Packages
- Oxygen Free Soldering
- Homogeneous temperature transmission

(\***Creative Vapor Phase Reflow Software**)

Condensation soldering also known as "Vapor Phase Reflow Soldering is the use of hot vapor, submitted by a special heat transfer medium, to transfer heat using the condensation principle on to a PCB with SMD components which then will be reflowed

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For contemporary complex BGA, FPGA and the new generation complex to solder SMD components, the condensation solder method is the only method which is relatively simple, The **IMDES CONDENS-IT PROFILER** family makes vapor phase reflow soldering process not any longer only available for the professional but also for the amateur and hobbyist, to achieve PERFECT solder results at a reasonable price.



Vapor Phase Reflow Soldering also known as " Condensation Soldering ", is a known technique that was applied in beginning of Eighties when the SMD technology was introduced. The heat transfer medium applied in those days used substances that were harmful to health and the environment.

As a result, the Vapor Phase Soldering lost popularity and Infrared soldering became the standard. The arrival of Perfluoropolyeter \* heralded the rebirth of Vapor Phase Reflow soldering technique.

Perfluoropolyeter \* is manufactured and marketed by the company Solvay Solexis under the trade name Galden